



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts,Customers Priority,Honest Operation,and Considerate Service",our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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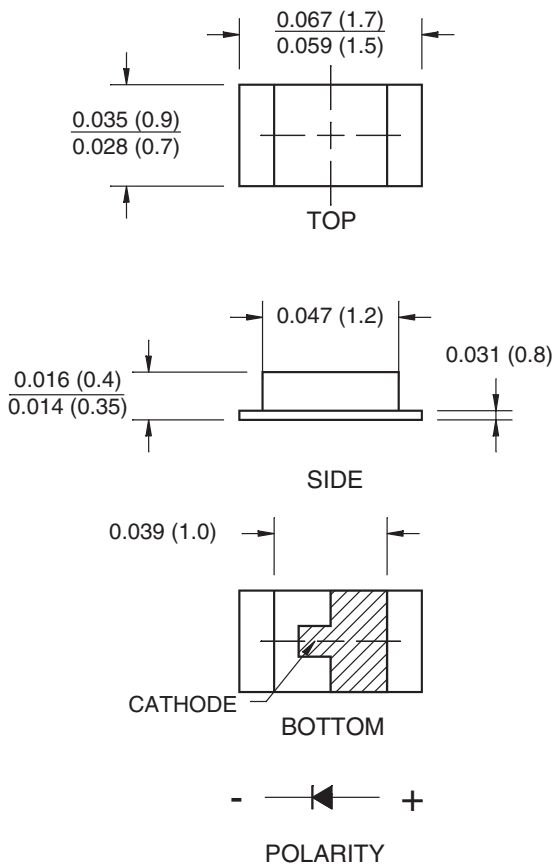
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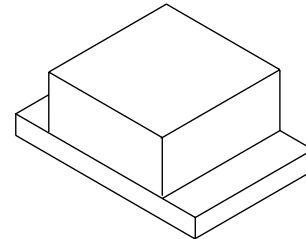


PACKAGE DIMENSIONS



NOTE:

Dimensions for all drawings are in inches (mm).



APPLICATIONS

- Keypad backlighting
- Push-button backlighting
- LCD backlighting

DESCRIPTION

This surface mount chip LED is designed to fit industry standard footprint. Small size, low profile and wide viewing angle make this LED an ideal choice for backlighting applications and panel illumination. This device utilizes an InGaN/Sapphire blue LED.

FEATURES

- Miniature footprint - 1.6(L) X 0.8(W) X 0.4(H) mm
- Wide viewing angle of 120°
- Water clear optics
- Moisture-proof packaging
- Available in 0.315" (8mm) width tape on 7" (178mm) diameter reel; 2,000 units per reel

QTLP603C-EB

Blue

ABSOLUTE MAXIMUM RATINGS ($T_A = 25^\circ\text{C}$ unless otherwise specified)

Parameter	Symbol	Rating	Unit
Operating Temperature	T_{OPR}	-40 to +85	$^\circ\text{C}$
Storage Temperature	T_{STG}	-40 to +90	$^\circ\text{C}$
Lead Soldering Time	T_{SOL}	260 for 5 sec	$^\circ\text{C}$
Continuous Forward Current	I_F	30	mA
Peak Forward Current ($f = 1.0 \text{ KHz}$, Duty Factor = 1/10)	I_{FM}	100	mA
Reverse Voltage	V_R	5	V
Power Dissipation	P_D	80	mW

ELECTRICAL / OPTICAL CHARACTERISTICS ($T_A = 25^\circ\text{C}$)

Part Number	QTLP603C-EB.7800D	Condition
Luminous Intensity (mcd)		$I_F = 5 \text{ mA}$
Bin I1	8 - 16	
Bin I2	13 - 26	
Forward Voltage (V)		$I_F = 5 \text{ mA}$
Bin V1	2.75 - 2.95	
Bin V2	2.95 - 3.15	
Dominant Wavelength (nm)		$I_F = 5 \text{ mA}$
Bin W1	465 - 470	
Bin W2	470 - 475	
Spectral Line Half Width (nm)	35	$I_F = 20 \text{ mA}$
Viewing Angle ($^\circ$)	120	$I_F = 20 \text{ mA}$

QTLP603C-EB

Blue

TYPICAL PERFORMANCE CURVES

Fig. 1 Forward Current vs. Forward Voltage

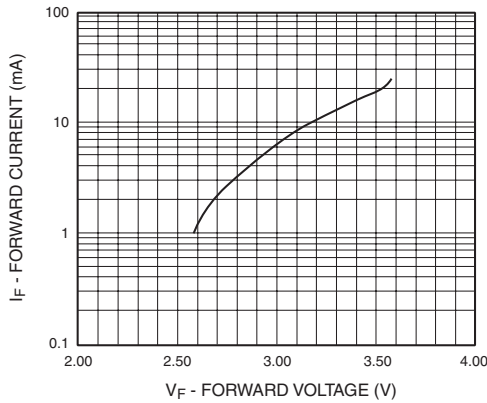


Fig. 2 Relative Luminous Intensity vs. DC Forward Current

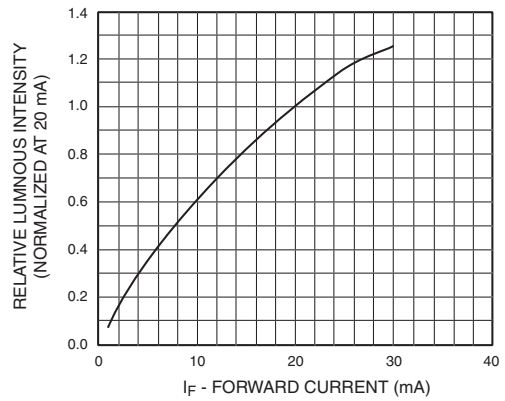


Fig. 3 Relative Intensity vs. Peak Wavelength

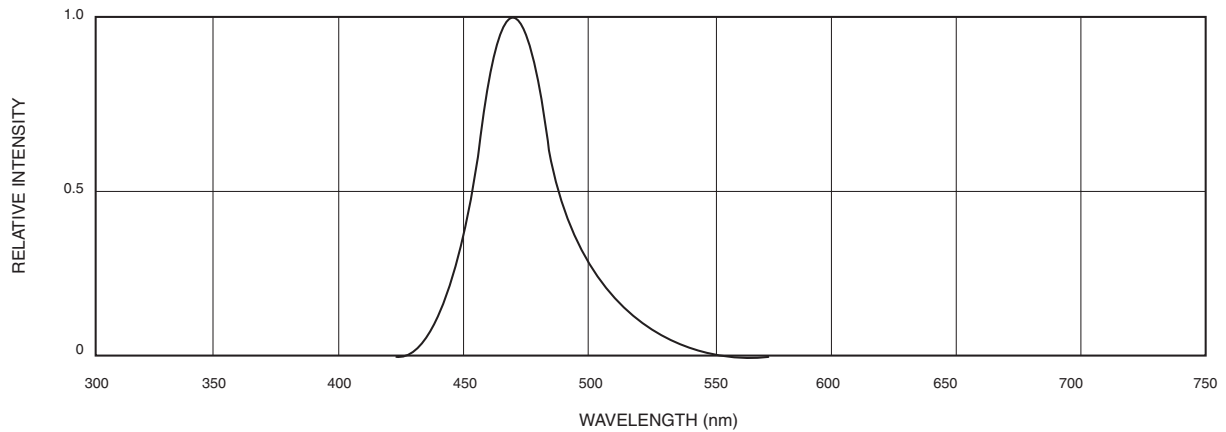


Fig.4 Radiation Diagram

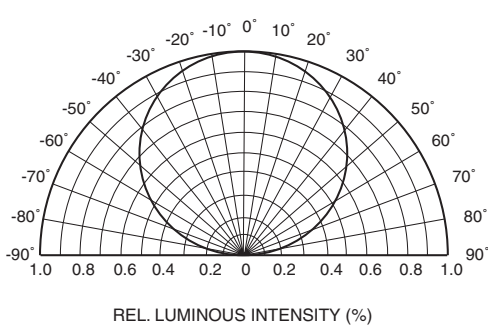
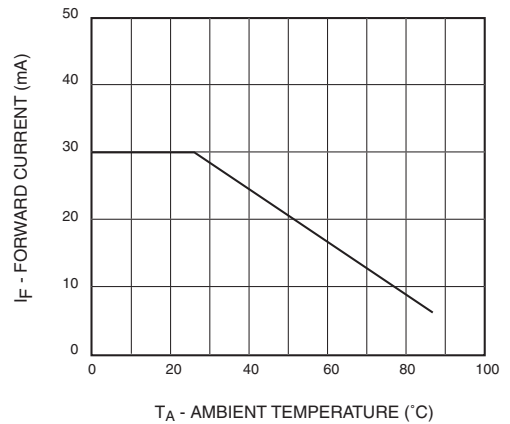


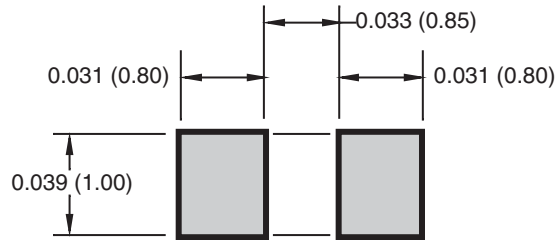
Fig.5 Maximum Forward Current vs. Ambient Temperature



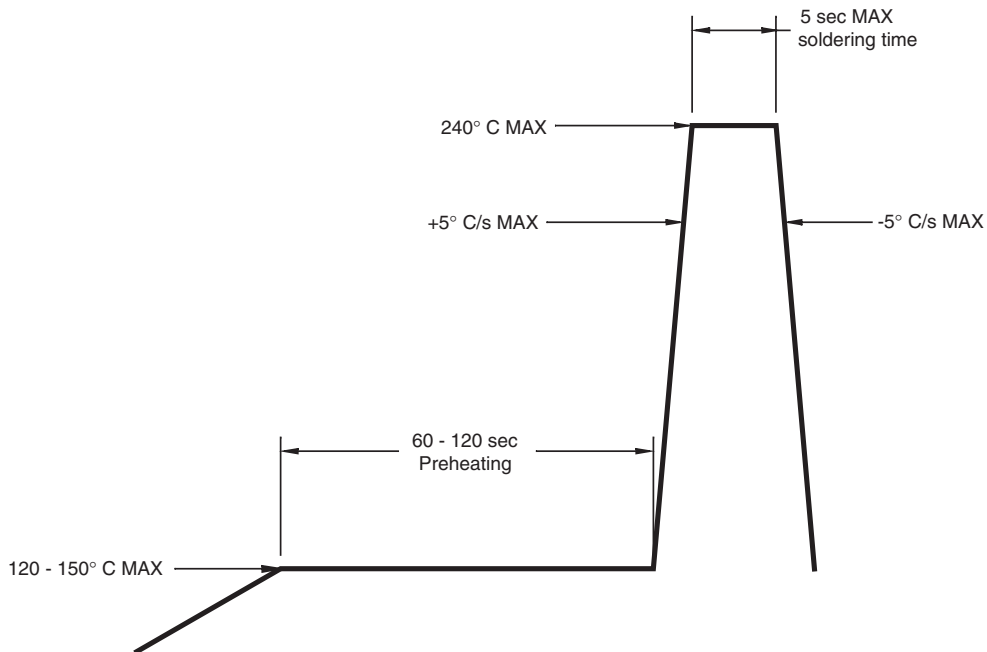
QTLP603C-EB

Blue

RECOMMENDED PRINTED CIRCUIT BOARD PATTERN



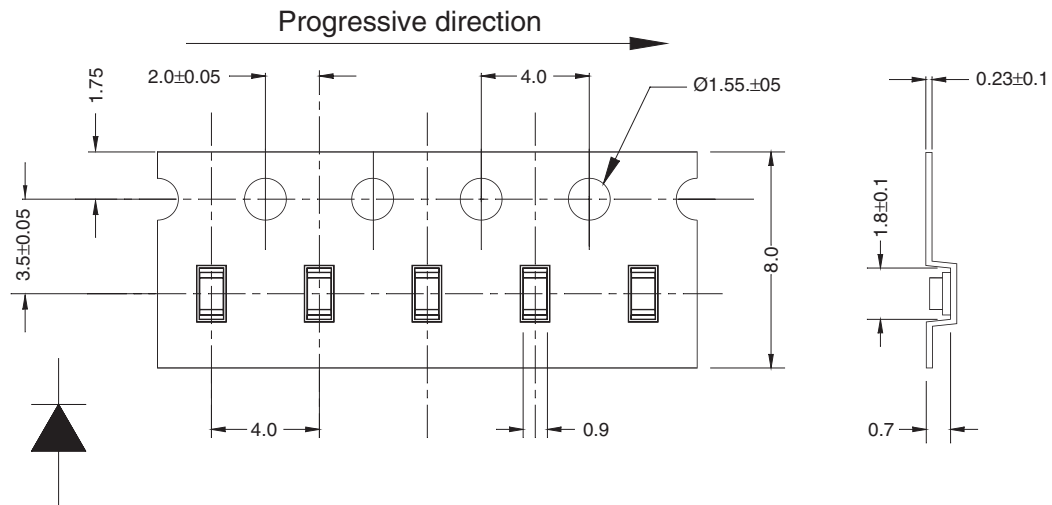
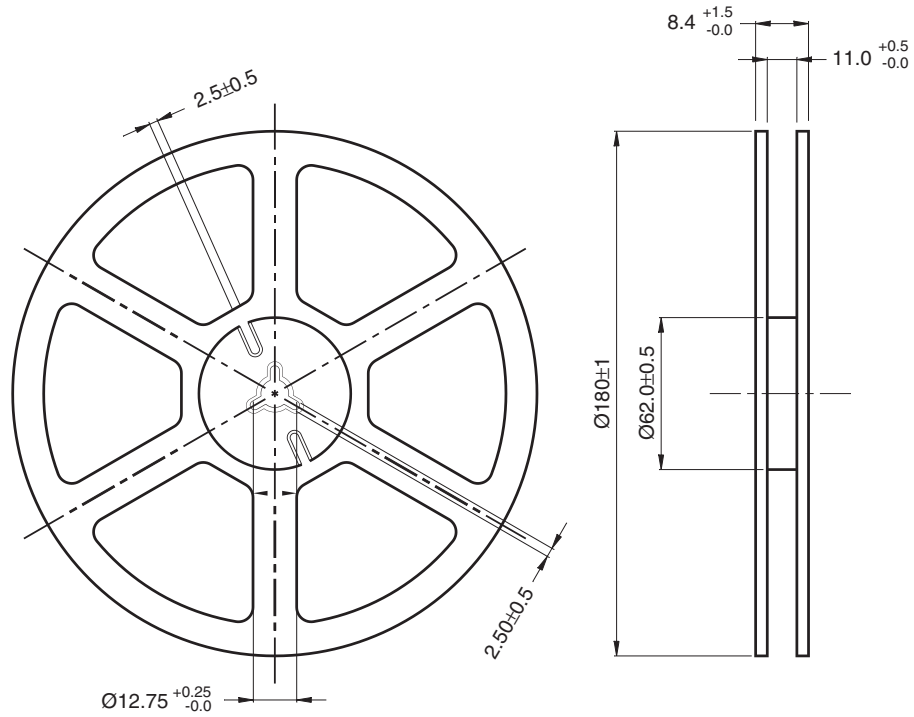
RECOMMENDED IR REFLOW SOLDERING PROFILE



QTLP603C-EB

Blue

TAPE AND REEL DIMENSIONS



Dimensional tolerance is ± 0.1 mm unless otherwise specified

Angle: ± 0.5

Unit: mm

Polarity

QTLP603C-EB

Blue

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